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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: HAMASAKI, et al.

Serial No.: 10/814,180

Filed: April 1, 2004

Title: METHOD OF RESIN-SEALING A
SEMICONDUCTOR DEVICE, AND
FORMING DIE FOR RESIN SEALING
THE SEMICONDUCTOR DEVICE

Atty. Dkt.: 01-615

Art Unit: 2825

Examiner: MALSAWMA

Commissioner for Patents
U.S. Patent and Trademark Office
Customer Window, Mail Stop Amendment
Randolph Building
401 Dulany St.
Alexandria, VA 22314

Date: 25 February 2005

AMENDMENT UNDER 37 CFR 1.111

Sir:

In response to the office action mailed 19 November 2004, please amend the application
as follows:

Amendments to the Claims are reflected in the listing of claims that begins on page 2 of
this paper.

Remarks begin on page 5 of this paper.